## 2SK1605

### Silicon N-Channel Power F-MOS FET

#### ■ Features

• High avalanche energy capacity

• V<sub>GSS</sub>: 30V guaranteed

lacktriangle Low  $R_{DS(on)}$ , high-speed switching characteristic

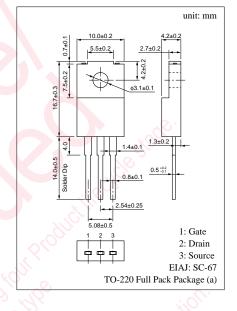
#### ■ Applications

• High-speed switching (switching power supply)

• For high-frequency power amplification

#### ■ Absolute Maximum Ratings $(T_C = 25^{\circ}C)$

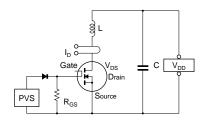
Parameter		Symbol	Ratings	Unit	
Drain to Source breakdown voltage		V <sub>DSS</sub>	450	V	
Gate to Source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC	$I_D$	±5	A	
	Pulse	$I_{DP}$	±10	A	
Avalanche energy capacity		EAS*	100	mJ	
Allowable power	$T_C = 25^{\circ}C$	D	50	W	
dissipation	$Ta = 25^{\circ}C$	$P_{D}$	2	W	
Channel temperature		$T_{ch}$	150	°C	
Storage temperature		$T_{\rm stg}$	-55 to +150	°C	



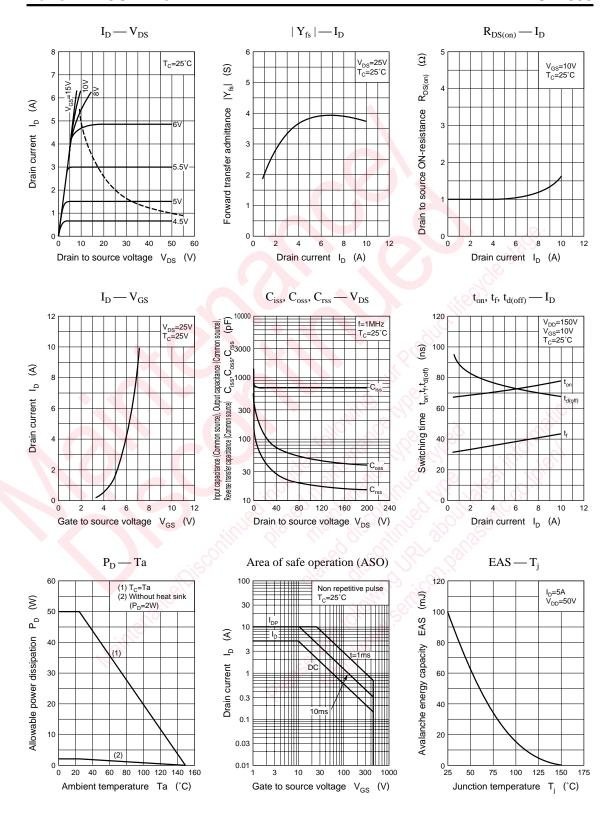
## ■ Electrical Characteristics (T<sub>C</sub> = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	$I_{DSS}$	$V_{DS} = 360V, V_{GS} = 0$	J. "	S XS	0.1	mA
Gate to Source leakage current	$I_{GSS}$	$V_{GS} = \pm 30V, V_{DS} = 0$	1, 7,4	1/0/	±1	μΑ
Drain to Source breakdown voltage	V <sub>DSS</sub>	$I_D = 1 \text{mA}, V_{GS} = 0$	450	977, 4		V
Avalanche energy capacity	EAS*	$L = 8mH$ , $I_D = 5A$ , $V_{DD} = 50V$	100			mJ
Gate threshold voltage	V <sub>th</sub>	$V_{DS} = 25V$ , $I_D = 1mA$	1	311	5	V
Drain to Source ON-resistance	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_D = 3A$		1	1.3	Ω
Forward transfer admittance	Y <sub>fs</sub>	$V_{DS} = 25V, I_D = 3A$	2	3.2		S
Input capacitance (Common Source)	C <sub>iss</sub>	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$	(S),	700		pF
Output capacitance (Common Source)	C <sub>oss</sub>			100		pF
Reverse transfer capacitance (Common Source)	C <sub>rss</sub>	jis Hall		40		pF
Turn-on time	t <sub>on</sub>	V 10V 10 24 VO.		70		ns
Fall time	$t_{\rm f}$	$V_{GS} = 10V, I_D = 3A$		35		ns
Turn-off time (delay time)	$t_{d(off)}$	$V_{DD} = 150V, R_L = 50\Omega$		80		ns

<sup>\*</sup> Avalanche energy capacity test circuit



<sup>\*</sup> Single pulse



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